1D.	S	4/12/64						Sh	aat 1	of 1	
FORM PTO-			U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY, DOCKET NO. 107317-00064			Sheet 1 of 1 SERIAL NO. New Appln			
LIST	LIST OF REFERENCES CITED BY APPLICANT					APPLICANT 10/821841 Kenji MARUYAMA et al					
		(Use several sheet	s if necessary)		FILING DATE April 12, 2004			GROUP 2812			
<u> </u>			U.S. PA	TENT DOCUMENT	s		<u></u>		-		
EXAMINER INITIAL		DOCUMENT NO.	DOCUMENT			CLASS CLASS					
94	AA	5,995,359	11/30/99	KLEE et al							
Gu	AB	6,258,459 B1	7/10/01	NOGUCHI et al							
	AC									_	
	AD								·		
,	AE										
	_AE					<u> </u>	i i				
			FOREIGN	PATENT DOCUME	NTS						
		DOCUMENT NO.	DATE	COUNTR		CLASS	SUB- CLASS	TRANSLATION YES NO PART.			
$\mathcal{O}_{\mathcal{U}}$	AG	10-189887	7/21/98	Japan				хх			
V	АН								/		
	AI								·		
	AJ										
	AK										
	AL		,	·	-						
		OTHER REFE	RENCES (Includi	ng Author, Title, Dat	te. Pertinent l	Pages Ftr					
					,	-3-0, -10					
	AM										
	AN										
	AO									g	
								,		<i> </i>	
EXAMINER	Mi	S M.	kuued	DATE CON	SIDERED C	2 2	2005	5		•	
*EXAMINE	R: Ini	ital if reference considere	whether or not cita	tion is in conformance w	th MPEP 609: D	raw line thm			in		

FORM PTO-1449

U.S. SEPARTMENT OF COMMERCE TRABBLENT AND TRADEMARK OFFICE

Sheet 1 of 1 ATTY. DOCKET NO. SERIAL NO. 107317-00064 10/821.841 APPLICANT

LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

MARUYAMA, et al. FILING DATE GROUP April 12, 2004 2812

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
M	AA	5,192,723	March 9, 1993	Fujiu et al.			1
Ou	AB	6,194,753 B1	February 27, 2001	Seon et al.			
CH	AC	2001/0005026 A1	June 28, 2001	Nakamura			
QU	AD	5,514,484	May 7, 1996	Nashimoto			
De	ΑĘ	5,623,439	April 22, 1997	Gotoh et al.			
6	AF						

FOREIGN PATENT DOCUMENTS

		† 		· ATENT BOODINEITTO				
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION YES NO PART.	
Au.	AG	EP 0 957 516 A1	March 24, 1997	Europe		٢		
Qu	АН	EP 0795 898 A2	March 10, 1997	Europe		-		
	Al							
	AJ							
	AK							
	AL							

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

94	АМ	P.C. Van Buskirk et al., "Common and Unique Aspects of Perovskite Thin Film CVD Processes" Integrated Ferroelectrics, Vol. 21, pgs. 273-289, (1998).
	AN	
	_AO	

EXAMINER Wind M. Lemula	DATE CONSIDERED Walch 22, 200,5
*FXAMINER: Initiality of company considered.	

ed, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

سنة	4				•					
	_	NPE						Sheet	1 of	
FORM PTO-1449 SE 1 3 2004 To			U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY, DOCKET NO.			SERIAL NO.		
					107317-0006	34		10/821,841		
	0E D	1	§/	IOANIT	APPLICANT					
LIST	OF RE	EFECTION OF THE PROPERTY OF TH	TED BY APPLI	ICANI	MARUYAMA	et al				
	(1	Use several sheets	s if necessary)		FILING DATE			GROUP		
				·	April 12, 200	4		2812		
		_	U.S. PATE	ENT DOCUMENT	<u>'S</u>					
EXAMINER'S INITIALS		DOCUMENT NO.	DATE	NA NA	.ME	CLASS	SUB- CLASS	FILING		
OU	AA	5,995,359	11/30/1999	Kiee et al		1	1	1		
94	AB	6,258,459	7/10/2001	Noguchi et al						
	AC									
	AD						/			
	AE		·			/				
	AF									
	1	<u> </u>	EODEIGN B/	TENT DOCUME	NTC (
		DOCUMENT	FOREIGN PATENT DOCUME				SUB-	B- TRANSLATION		
		NO.	DATE	COUN	COUNTRY CL		CLASS	YES NO PART		
	AG									
	АН									
	Al.									
·¥·	LA					÷				
	AK			<u> </u>					 	
	AK								 	
	AL		<u> </u>	<u> </u>					<u>l</u>	
		OTHER REFER	RENCES (Including	Author, Title, Da	te, Pertinent F	Pages, Etc	<u>;.) </u>			
						•			•	
	AM									
		,							********	
	AN .									
	-									
	AO								•	
		· .								
EXAMINER			, /	DATE CON	SIDERED					
Qui.	11.11	M. Le	11110 8	1 UN	larch	22	20	6		
	ヘノタール	111000004	いんりく レフ	. <i>V</i> //	i U/I/I/A	- 1261	~ <i>~</i>	r: 1 1		

*EXAMINER: Writial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.